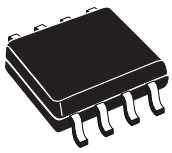
STS4DNF60

N-channel 60V - 0.070Ω - 4A - SO-8
STripFET™ Power MOSFET

Features

Type	V_{DSS}	$R_{DS(on)}$	I_D
STS4DNF60	60V	<0.090Ω	4A

- Standard outline for easy automated surface mount assembly
- Low threshold drive

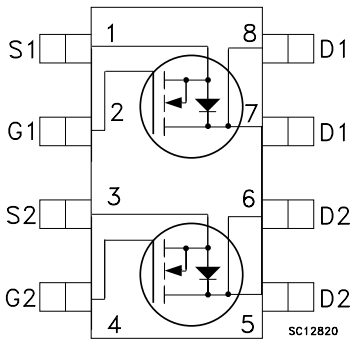


SO-8

Description

This Power MOSFET is the latest development of STMicroelectronics unique “Single Feature Size™” strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

Internal schematic diagram



Application

- Switching application

Order code

Part number	Marking	Package	Packaging
STS4DNF60	S4DNF60	SO-8	Tape & reel

Contents

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage (V_{GS} = 0)	60	V
V_{GS}	Gate- source voltage	± 20	V
I_D	Drain current (continuous) at T_C = 25°C	4	A
I_D	Drain current (continuous) at T_C = 100°C	2.5	A
I_{DM} (1)	Drain current (pulsed)	16	A
P_{TOT}(2)	Total dissipation at T_C = 25°C	2	W
T_j T_{stg}	Operating junction temperature Storage temperature	-55 to 150	°C

1. Pulse width limited by safe operating area
2. P_{TOT}=1.6W for single operation

Table 2. Thermal data

Symbol	Parameter	Value	Unit
Rthj-pcb	Thermal resistance junction-pcb D.O.(1)	62.5	°C/W

1. When mounted on inch² FR-4 board, 2 Oz Cu, t ≤ 10sec, dual operation

2 Electrical characteristics

(Tcase =25°C unless otherwise specified)

Table 3. On /off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 250µA, V_{GS} = 0	60			V
I_{DSS}	Zero gate voltage drain current (V_{GS} = 0) V_{DS} = Max rating V_{DS} = Max rating, T_C=125°C				1 10	µA µA
I_{GSS}	Gate-body leakage current (V_{DS} = 0)	V_{GS} = ± 20V			± 100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250µA	2		4	V
$R_{DS(on)}$	Static drain-source on resistance	V_{GS} = 10V, I_D = 2A		0.070	0.090	Ω

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
g_{fs}	Forward transconductance	V_{DS} =25V, I_D= 2A		25		S
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V_{DS} = 25 V, f = 1 MHz, V_{GS} = 0		315 70 30		pF pF pF
Q_g Q_{gs} Q_{gd}	Total gate charge Gate-source charge Gate-drain charge	V_{DD} = 48V, I_D = 4A, V_{GS} = 10V (see *Figure 12*)		10 3.5 3.5		nC nC nC

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
$t_{d(on)}$ t_r	Turn-on delay time Rise time	V_{DD} = 30V, I_D = 2A, R_G = 4.7Ω, V_{GS} = 10V (see *Figure 11*)		7 18		ns ns
$t_{d(off)}$ t_f	Turn-off delay time Fall time	V_{DD} = 30V, I_D = 2A, R_G = 4.7Ω, V_{GS} = 10V (see *Figure 11*)		17 6		ns ns

Table 6. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD} I_{SDM} (1)	Source-drain current Source-drain current (pulsed)				4 16	A A
V_{SD} (2)	Forward on voltage	I_{SD} = 4A, V_{GS} = 0			1.2	V
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD} = 4A, di/dt = 100A/µs V_{DD} = 20V, T_j = 25°C (see *Figure 16*)		45 68 3		ns nC A
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	I_{SD} = 4A, di/dt = 100A/µs V_{DD} = 20V, T_j = 150°C (see *Figure 16*)		50 88 3.5		ns nC A

1. Pulse width limited by safe operating area
2. Pulsed: Pulse duration = 300 µs, duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

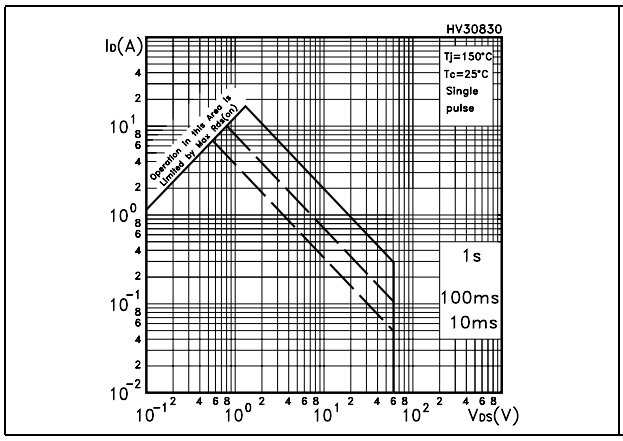


Figure 2. Thermal impedance

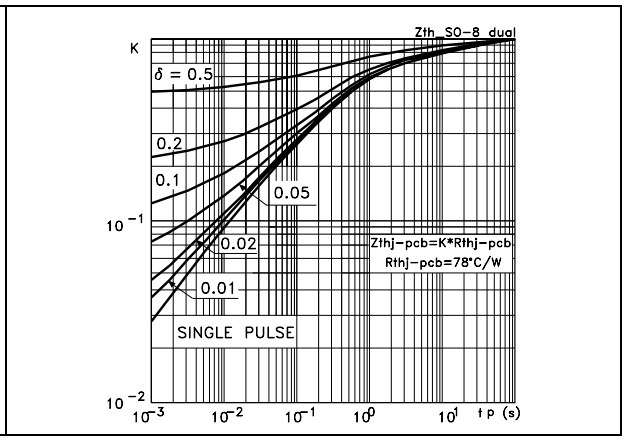


Figure 3. Output characteristics

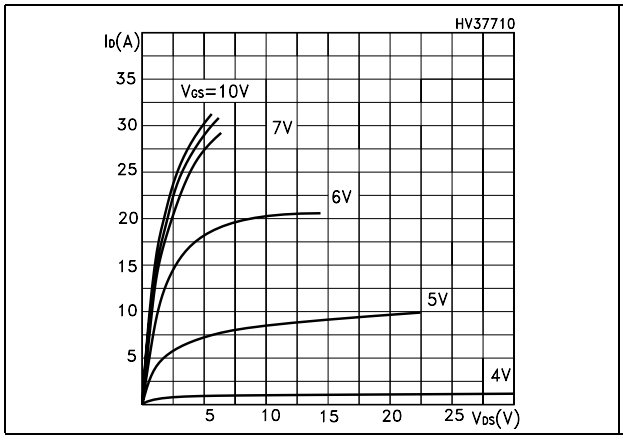


Figure 4. Transfer characteristics

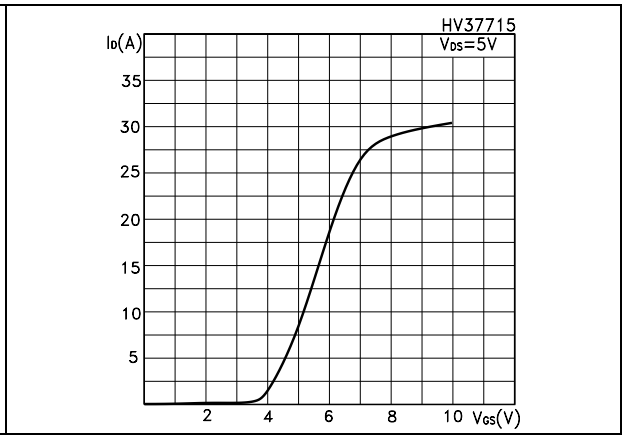


Figure 5. Source-drain diode forward characteristics

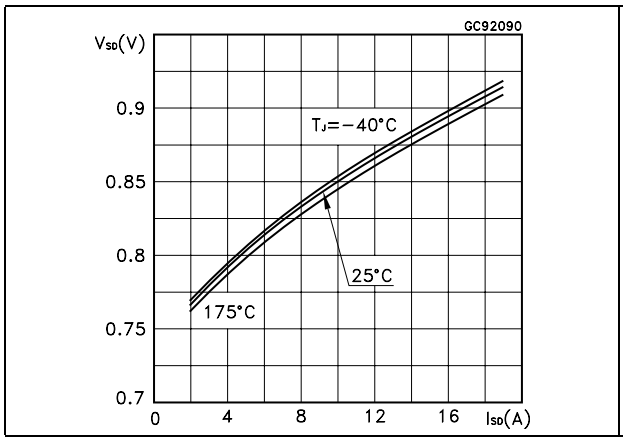


Figure 6. Static drain-source on resistance

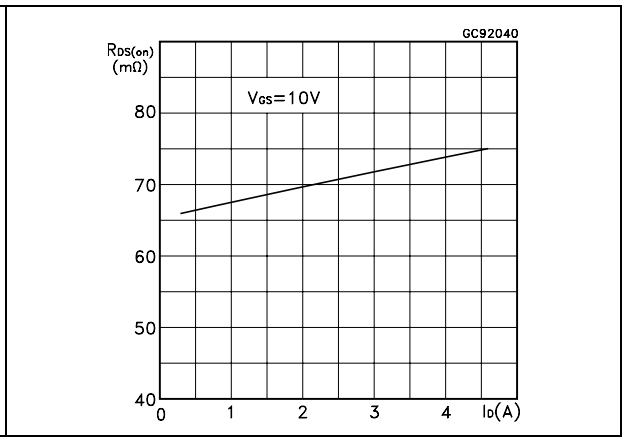


Figure 7. Gate charge vs gate-source voltage

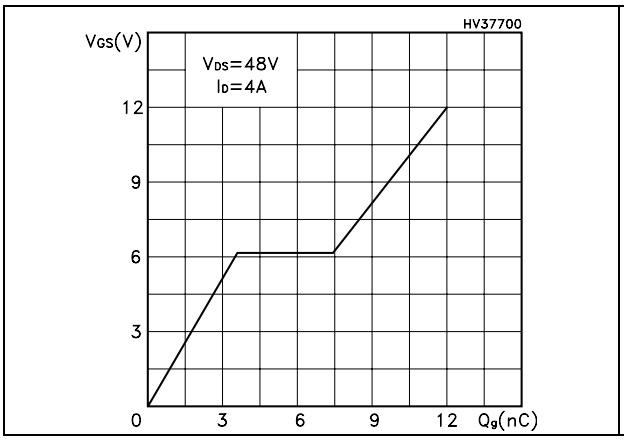


Figure 8. Capacitance variations

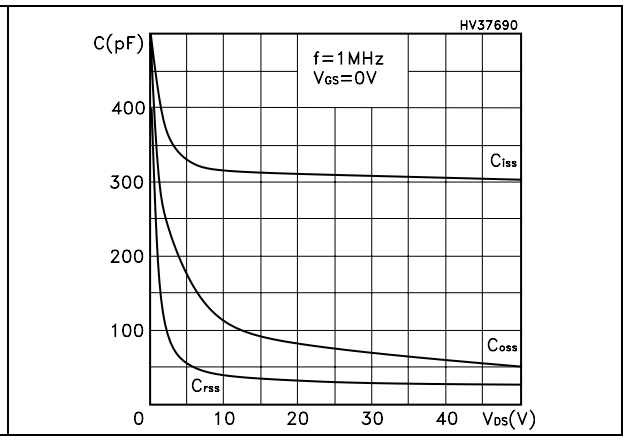


Figure 9. Normalized gate threshold voltage vs temperature

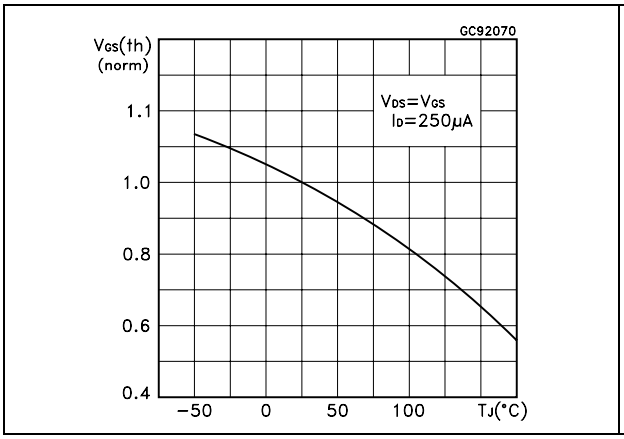
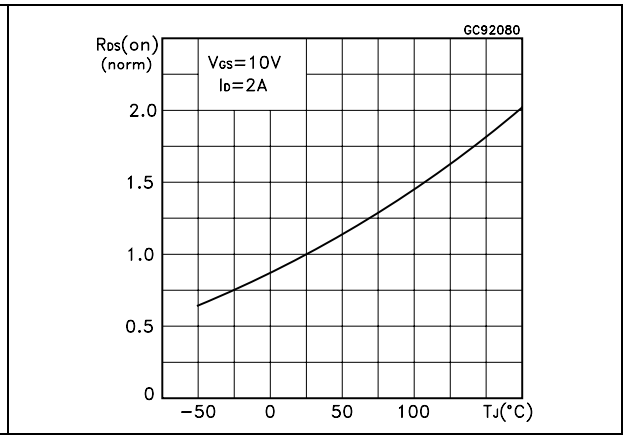


Figure 10. Normalized on resistance vs temperature



3 Test circuits

Figure 11. Switching times test circuit for resistive load

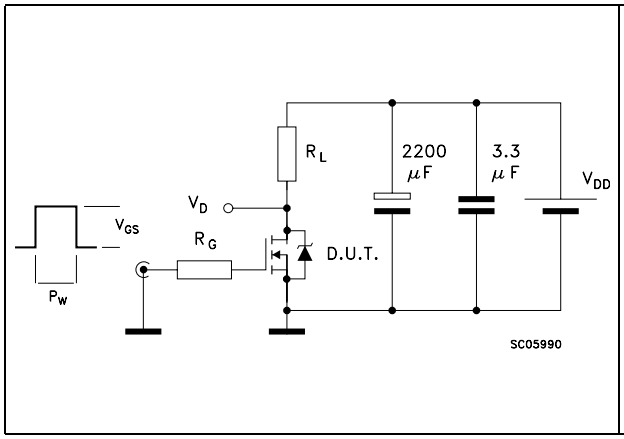


Figure 12. Gate charge test circuit

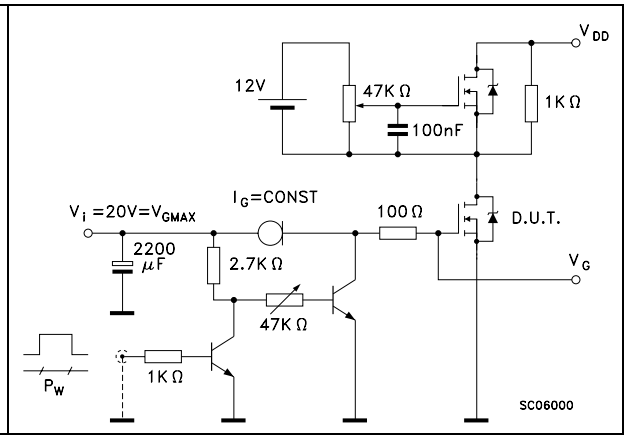


Figure 13. Test circuit for inductive load switching and diode recovery times

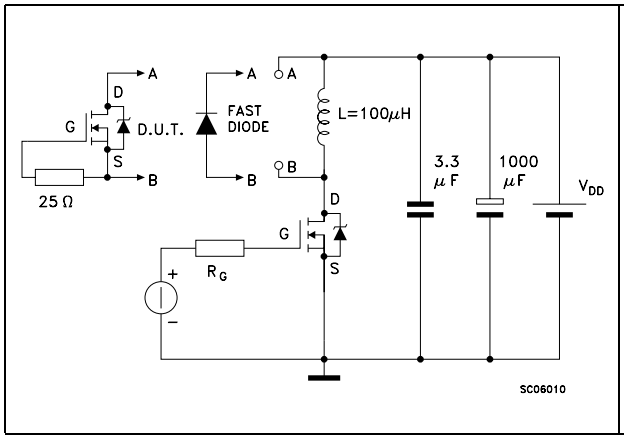


Figure 14. Unclamped Inductive load test circuit

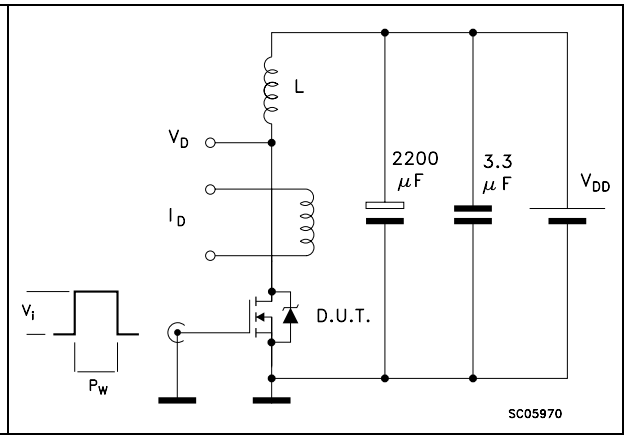


Figure 15. Unclamped inductive waveform

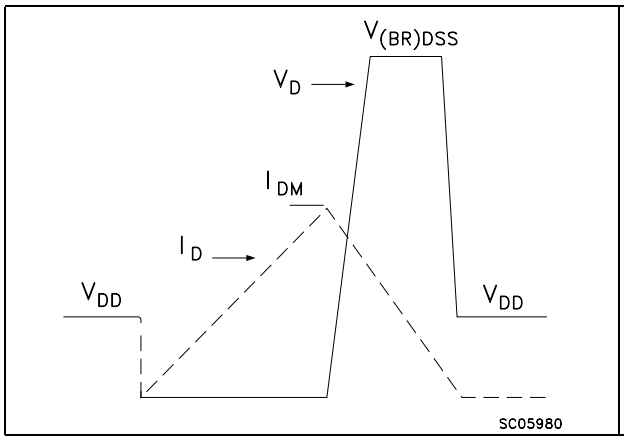
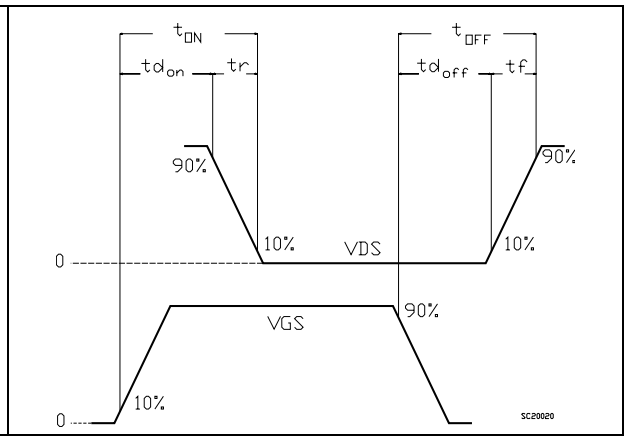


Figure 16. Switching time waveform

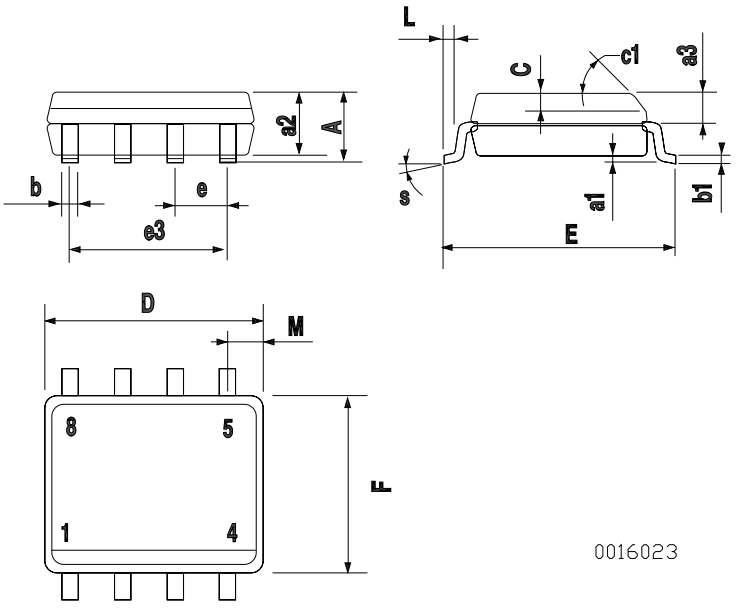


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: *www.st.com*

SO-8 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A			1.75			0.068
a1	0.1		0.25	0.003		0.009
a2			1.65			0.064
a3	0.65		0.85	0.025		0.033
b	0.35		0.48	0.013		0.018
b1	0.19		0.25	0.007		0.010
C	0.25		0.5	0.010		0.019
c1	45 (typ.)					
D	4.8		5.0	0.188		0.196
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		3.81			0.150	
F	3.8		4.0	0.14		0.157
L	0.4		1.27	0.015		0.050
M			0.6			0.023
S	8 (max.)					



5 Revision history

Table 7. Revision history

Date	Revision	Changes
17-May-2007	1	First release

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